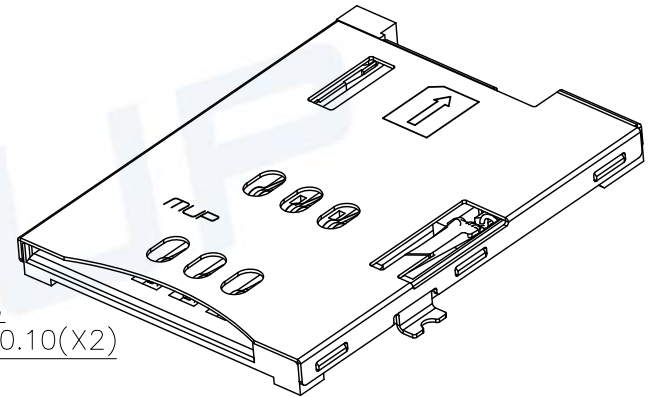
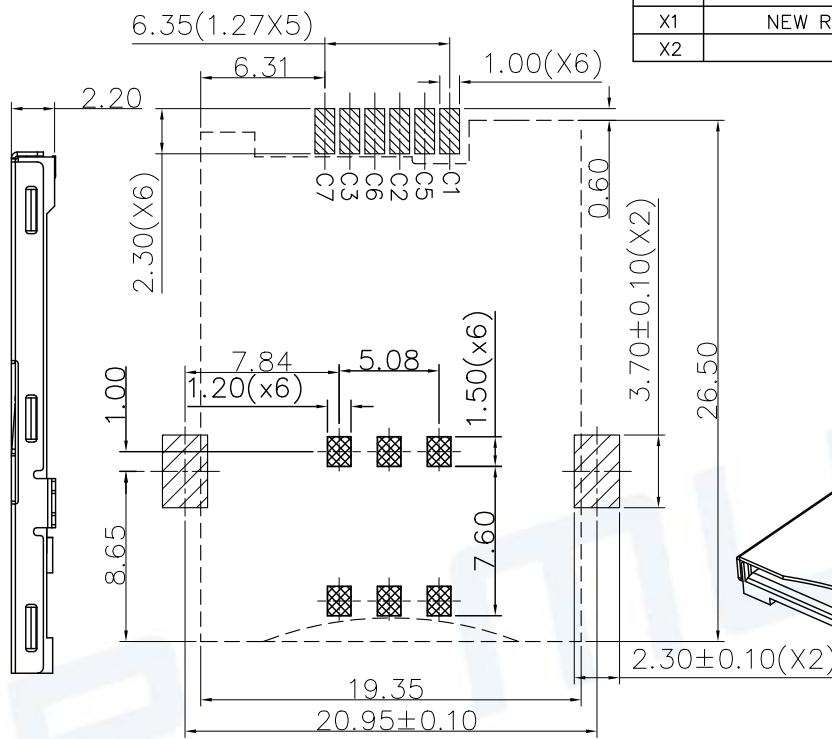
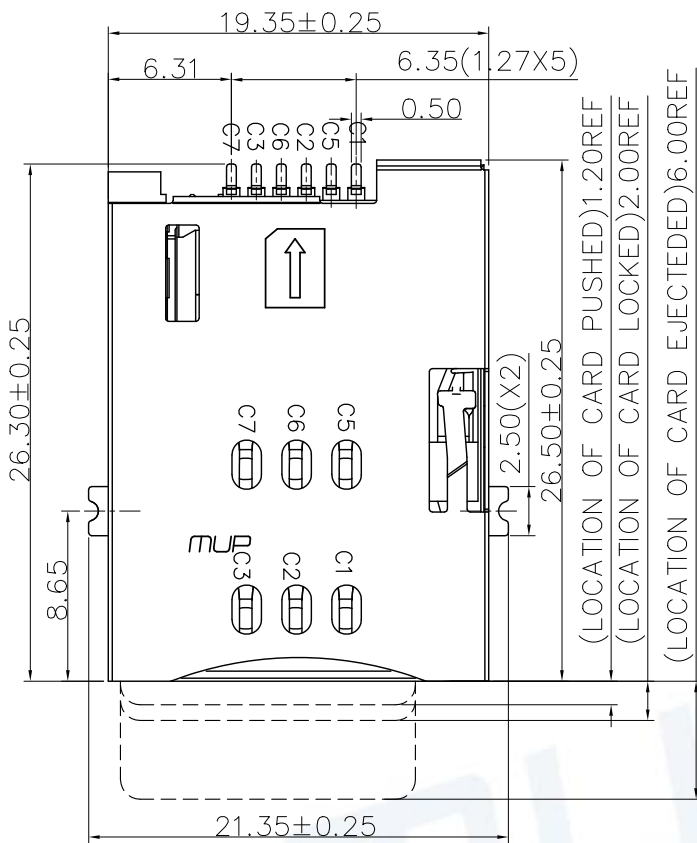
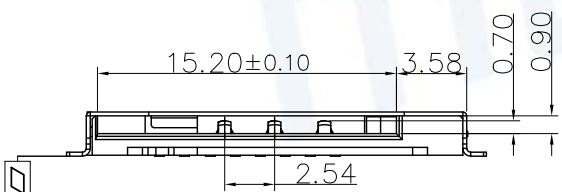


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1	NEW REVISION				Henry Jul.08.2016
X2					



RECOMMENDED P.C.B LAYOUT  
COMPONENT SIDE(TOLERANCE ±0.05)

- PAD AREA
- CONNECTOR OUTLINE
- NO PATTERN AND VIA HOLE IN THIS AREA



Micro SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

**TECHNICAL CHARACTERISTICS**  
 1.General Characteristics  
 Dimensions: 26.50LX19.35WX2.20H mm  
 Weight: Approx 1.50±0.1g  
 Durability:5,000 cycles min.  
 2.Electrical Characteristics  
 Contact resistance: 50mΩ typical,100mΩ max  
 Insulation resistance:>1000MΩ/500V DC  
 3.Solderability  
 Vapor phase: 215°C,30sec.Max  
 IR reflow: 250°C,5sec.Max  
 Manual soldering: 370°C,3sec.Max  
 4.Environmental Characteristics  
 Operating temperature: -40°C~+85°C  
 Operating humidity: 10%~+95%RH

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Contact: Au plated, Tin plating on solder tails. Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	
3	SHELL	1	Stainless Steel	SMT area: Au plated
4	COIL SPRING	1	SWP	
5	HEART CAM	1	Hi-temp Thermoplastic	Black UL94V-0
6	CAM PIN	1	Stainless Steel	

Unless otherwise specified, other tolerance are:

**MUP MUP INDUSTRIAL CO.,LTD.**

X ±0.35	X' ±5'	NAME: <b>SIM Card Connector</b>	
X.X ±0.25	X.X' ±4'	MODEL NO: <b>MUP-C759-2</b>	
X.XX ±0.15	X.XX' ±3'	TYPE: <b>H2.20 mm without post</b>	
X.XXX ±0.10	X.XXX' ±2'		
PROJ.	UNIT	SCALE	DRAWN
	mm	1:1	Henry Jul.08.2016
CUSTOMER DRAWING			CHECKED
			Henry Jul.08.2016
			APPROVAL
			Simon Jul.08.2016
		DWG NO.:	DWG-MUP-C759-2
		SHEET	1/1
		REVISION	X1

